

SN74AHCT1G08 Single 2-Input Positive-AND Gate

1 Features

- Operating range: 4.5V to 5.5V
- Maximum t_{pd} of 7.1ns at 5V
- Low power consumption: maximum I_{CC} of 10 μ A
- ± 8 mA output drive at 5V
- Inputs are TTL-voltage compatible
- Latch-up performance exceeds 250 mA per JESD 17

2 Applications

- TV, Set-Top Box, and Audio
- Wireless Infrastructure
- Factory Automation and Control
- PC and Notebooks
- Building Automation
- Grid Infrastructure
- Medical, Healthcare, and Fitness
- Printers
- Test and Measurement
- EPOS (Electronic Point of Sale)
- Telecom Infrastructure
- Projectors

3 Description

The SN74AHCT1G08 device is a single 2-input positive-AND gate. The device performs the Boolean function $Y = A \times B$ or $Y = \overline{A + B}$ in positive logic. Low I_{CC} current allows this device to be used in power-sensitive or battery-powered applications.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾	BODY SIZE ⁽³⁾
SN74AHCT1G08	DBV (SOT-23, 5)	2.9mm × 2.8mm	2.9mm × 1.6mm
	DCK (SC70, 5)	2.00mm × 1.25mm	2.00mm × 1.25mm
	DRL (SOT, 5)	1.60mm × 1.6mm	1.60mm × 1.2mm

- (1) For all available packages, see the orderable addendum at the end of the data sheet.
- (2) The package size (length × width) is a nominal value and includes pins, where applicable.
- (3) The body size (length × width) is a nominal value and does not include pins.



Logic Diagram



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4 Pin Configuration and Functions

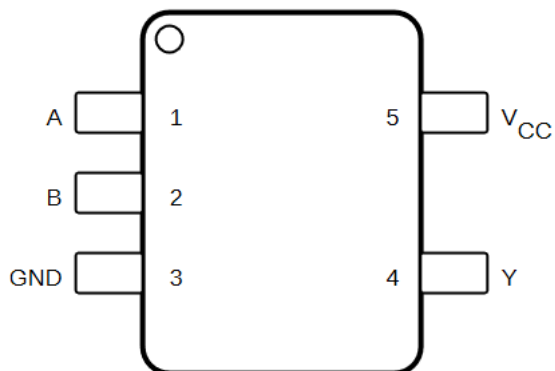


Figure 4-1. DBV, DCK, and DRL Packages 5-Pin SOT-23, SC70, and SOT (Top View)

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
A	1	I	Input A
B	2	I	Input B
GND	3	—	Ground Pin
V _{CC}	5	—	Supply Pin
Y	4	O	Output

(1) Signal Types: I = Input, O = Output, I/O = Input or Output

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted).⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	−0.5	7	V
V _I	Input voltage ⁽²⁾	−0.5	7	V
V _O	Output voltage ⁽²⁾	−0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		−20 mA
I _{OK}	Output clamp current	V _O < 0 or V _O > V _{CC}		±20 mA
I _O	Continuous output current	V _O = 0 to V _{CC}		±25 mA
	Continuous current through V _{CC} or GND			±50 mA
T _J	Maximum junction temperature			150 °C
T _{stg}	Storage temperature	−65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under [Section 5.3](#). Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2500
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	4.5	5.5	V
V _{IH}	High-level input voltage	2		V
V _{IL}	Low-level input voltage		0.8	V
V _I	Input voltage	0	5.5	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current		−8	mA
I _{OL}	Low-level output current		8	mA
Δt/Δv	Input transition rise and fall rate		20	ns/V
T _A	Operating free-air temperature	−40	125	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See TI application report, *Implications of Slow or Floating CMOS Inputs* (SCBA004).

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74AHCT1G08			UNIT
		DBV (SOT-23)	DCK (SC70)	DRL (SOT)	
		5 PINS	5 PINS	5 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	278	289.2	242.9	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	180.5	205.8	77.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	184.4	176.2	77.5	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	115.4	117.6	9.6	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	183.4	175.1	77.3	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bot) thermal resistance	N/A	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

5.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT	
V _{OH}	High-level output voltage	I _{OH} = −50 μA, V _{CC} = 4.5 V	T _A = 25°C	4.4	4.5	V		
			T _A = −40°C to 125°C	4.4				
		I _{OH} = −8 mA, V _{CC} = 4.5 V	T _A = 25°C	3.94				
			T _A = −40°C to 125°C	3.8				
V _{OL}	Low-level output voltage	I _{OL} = 50 μA, V _{CC} = 4.5 V				0.1	V	
		I _{OL} = 8 mA, V _{CC} = 4.5 V	T _A = 25°C			0.36		
			T _A = −40°C to 125°C			0.44		
I _I	Input current	V _I = 5.5 V or GND, V _{CC} = 0 V to 5.5 V	T _A = 25°C			±0.1	μA	
			T _A = −40°C to 125°C			±1		
I _{CC}	Supply current	V _I = V _{CC} or GND, I _O = 0, V _{CC} = 5.5 V	T _A = 25°C			1	μA	
			T _A = −40°C to 125°C			10		
ΔI _{CC} ⁽¹⁾	Change in supply current	One input at 3.4 V, Other Inputs at V _{CC} or GND, V _{CC} = 5.5 V	T _A = 25°C			1.35	mA	
			T _A = −40°C to 125°C			1.5		
C _I	Input capacitance	V _I = V _{CC} or GND, V _{CC} = 5 V				4	10	pF

(1) This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC} .

5.6 Switching Characteristics

over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

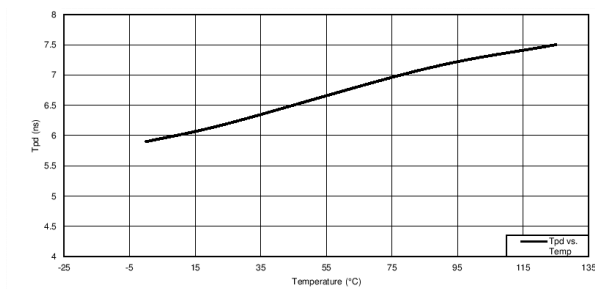
PARAMETER	FROM (INPUT)	TO (OUTPUT)	OUTPUT CAPACITANCE	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} Propagation delay, low to high transition	A or B	Y	$C_L = 15\text{ pF}$	$T_A = 25^\circ\text{C}$		5	6.2	ns
				$T_A = -40^\circ\text{C}$ to 85°C	1		7.1	
				$T_A = -40^\circ\text{C}$ to 125°C	1		7.5	
t_{PHL} Propagation delay, high to low transition	A or B	Y	$C_L = 15\text{ pF}$	$T_A = 25^\circ\text{C}$		5	6.2	ns
				$T_A = -40^\circ\text{C}$ to 85°C	1		7.1	
				$T_A = -40^\circ\text{C}$ to 125°C	1		7.5	
t_{PLH} Propagation delay, low to high transition	A or B	Y	$C_L = 50\text{ pF}$	$T_A = 25^\circ\text{C}$		5.5	7.9	ns
				Propagation delay, high to low transition	1		9	
				$T_A = -40^\circ\text{C}$ to 125°C	1		10	
t_{PHL} Propagation delay, high to low transition	A or B	Y	$C_L = 50\text{ pF}$	$T_A = 25^\circ\text{C}$		5.5	7.9	ns
				$T_A = -40^\circ\text{C}$ to 85°C	1		9	
				$T_A = -40^\circ\text{C}$ to 125°C	1		10	

5.7 Operating Characteristics

$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load, $f = 1\text{ MHz}$	18	pF

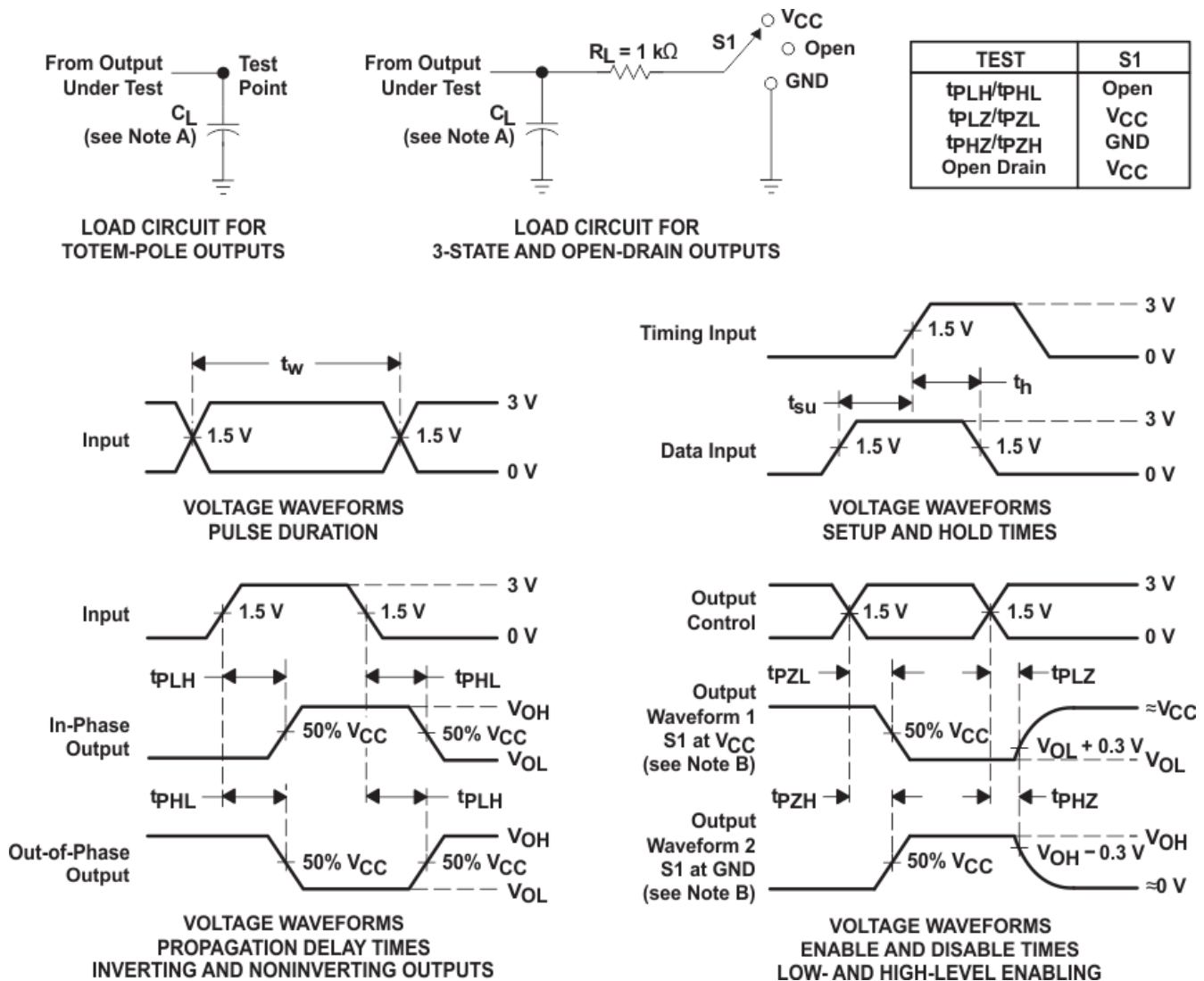
5.8 Typical Characteristics



$C_L = 15\text{ pF}$

Figure 5-1. T_{pd} vs Temperature

6 Parameter Measurement Information



C_L includes probe and jig capacitance.

Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.

Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

All input pulses are supplied by generators having the following characteristics: PRR $\leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.

The outputs are measured one at a time with one input transition per measurement.

All parameters and waveforms are not applicable to all devices.

Figure 6-1. Load Circuit and Voltage Waveforms

7 Detailed Description

7.1 Overview

The SN74AHCT1G08 device is a single 2-input positive-AND gate. The device performs the Boolean AND function ($Y = A \cdot B$ or $Y = \overline{A + B}$) in positive logic. Low I_{CC} current allows this device to be used in power-sensitive or battery-powered applications. Robust inputs allow the device to up-translate with a propagation delay of 20 ns.

7.2 Functional Block Diagram



Figure 7-1. Logic Diagram (Positive Logic)

7.3 Feature Description

The V_{CC} for the device is optimized at 5 V.

Up voltage translation from 3.3 V to 5 V is allowed. The inputs accept V_{IH} levels of 2 V.

Output ringing is minimized by slow edge rates.

Inputs are TTL-Voltage compatible.

7.4 Device Functional Modes

Table 7-1 lists the functional modes of the SN74AHCT1G08.

Table 7-1. Function Table

INPUTS ⁽¹⁾		OUTPUT ⁽²⁾
A	B	Y
H	H	H
L	X	L
X	L	L

(1) H = High Voltage Level, L = Low Voltage Level, X = Don't Care

(2) H = Driving High, L = Driving Low, Z = High Impedance State

8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

The SN74AHCT1G08 device is a single AND gate, which is often used for many common functions like power sequencing or an *on* LED indicator. Because the device is configured to output LOW unless all inputs are HIGH, an LED tied to the output of the device will only turn HIGH when all systems connected are sending a HIGH, or *ready* signal.

8.2 Typical Application

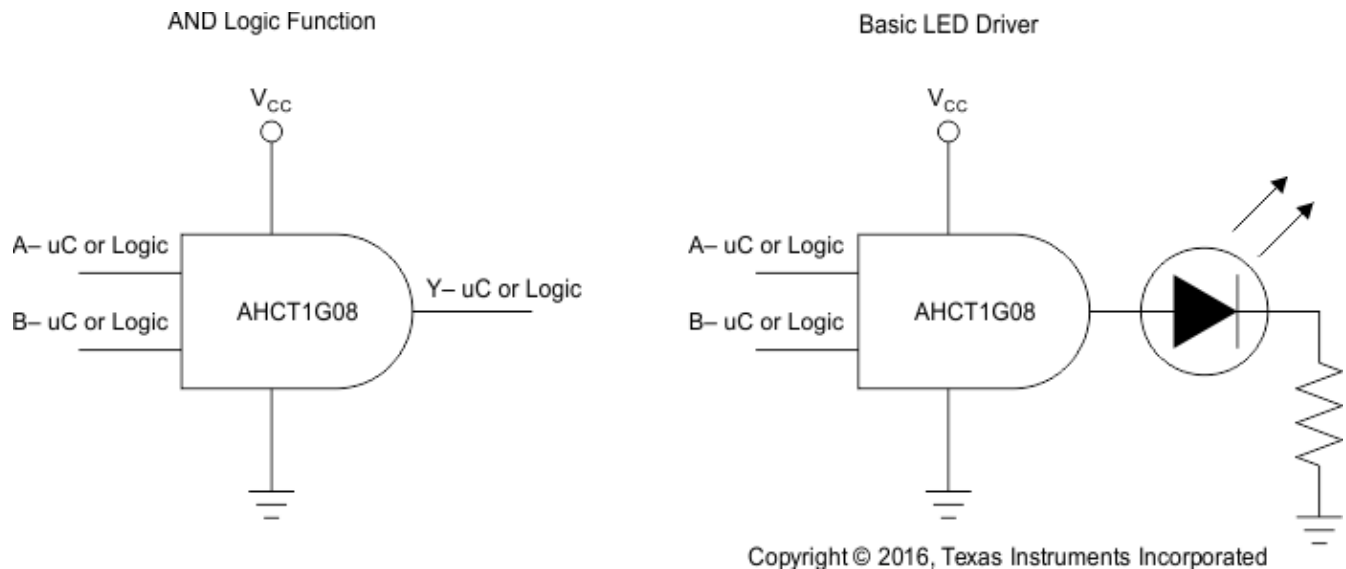


Figure 8-1. Typical Application Diagram

8.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive also creates fast edges into light loads, so routing and load conditions must be considered to prevent ringing.

8.2.2 Detailed Design Procedure

- Recommended Input Conditions
 - For rise time and fall time specifications, see $\Delta t/\Delta V$ in [Section 5.3](#).
 - For specified high and low levels, see V_{IH} and V_{IL} in [Section 5.3](#).
 - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC} .
- Recommended Output Conditions
 - Load currents must not exceed 25 mA per output and 50 mA total for the part.
 - Outputs must not be pulled above V_{CC} .

8.2.3 Application Curve

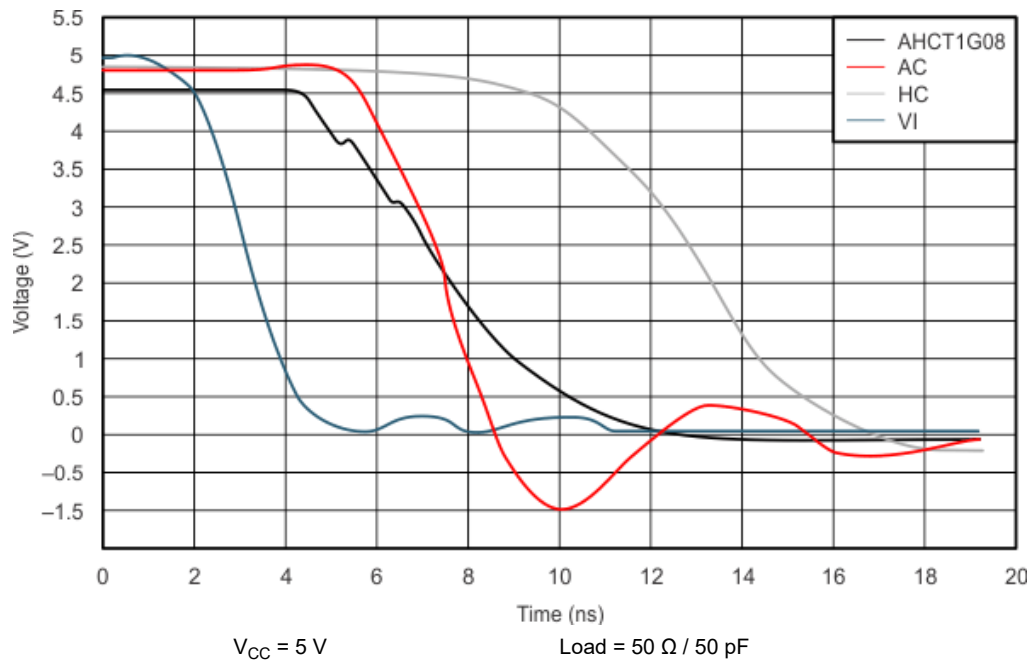


Figure 8-2. Typical Switching Characteristics

8.3 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in [Recommended Operating Conditions](#).

Each V_{CC} pin must have a good bypass capacitor to prevent power disturbance. TI recommends a 0.1- μF capacitor for devices with a single supply; and a 0.01- μF or 0.022- μF capacitor for each power pin if there are multiple V_{CC} pins. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. 0.1- μF and 1- μF capacitors are commonly used in parallel. The bypass capacitor must be installed as close to the power pin as possible for best results.

8.4 Layout

8.4.1 Layout Guidelines

When using multiple bit logic devices inputs must not ever float. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Observe the following rules under all circumstances.

- All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating.
- The logic level that must be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} , whichever make more sense or is more convenient.

8.4.1.1 Layout Example

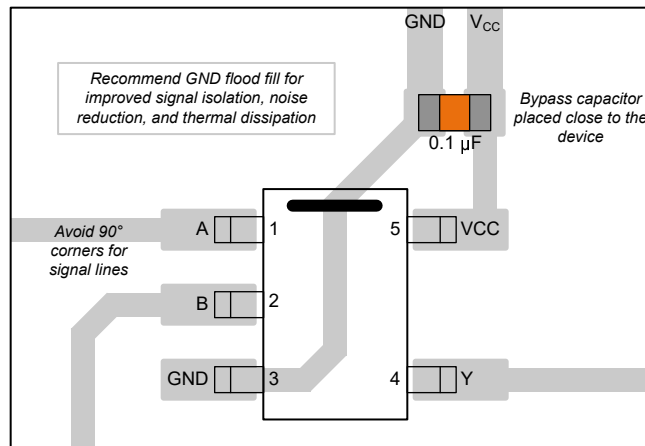


Figure 8-3. Layout Example for the SN74AHCT1G08

9 Device and Documentation Support

9.1 Documentation Support (Analog)

9.1.1 Related Documentation

For related documentation, see the following:

Implications of Slow or Floating CMOS Inputs, [SCBA004](#)

9.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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9.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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9.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision R (October 2023) to Revision S (February 2024)	Page
• Updated thermal values for DBV package from RθJA = 226 to 278, RθJC(top) = 165 to 180.5, RθJB = 59.1 to 184.4, ΨJT = 45.5 to 115.4, ΨJB = 58.3 to 183.4, RθJC(bot) = N/A, all values in °C/W	5

Changes from Revision Q (April 2016) to Revision R (October 2023)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Updated thermal values for DCK package from RθJA = 277.5 to 289.2, RθJC(top) = 92.9 to 205.8, RθJB = 64.2 to 176.2, ΨJT = 1.9 to 117.6, ΨJB = 63.5 to 175.1, RθJC(bot) = N/A, all values in °C/W	5

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74AHCT1G08DBVRG4	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B08G	Samples
74AHCT1G08DRLRG4	ACTIVE	SOT-5X3	DRL	5	4000	RoHS & Green	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	(BEB, BES)	Samples
SN74AHCT1G08DBV3	ACTIVE	SOT-23	DBV	5	3000	RoHS & Non-Green	SNBI	Level-1-260C-UNLIM	-40 to 125	B08Y	Samples
SN74AHCT1G08DBVR	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	(B083, B08G, B08J, B08L, B08S)	Samples
SN74AHCT1G08DCK3	ACTIVE	SC70	DCK	5	3000	RoHS & Non-Green	SNBI	Level-1-260C-UNLIM	-40 to 125	BEY	Samples
SN74AHCT1G08DCKR	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	(1PJ, BE3, BEG, BE J, BEL, BES)	Samples
SN74AHCT1G08DRLR	ACTIVE	SOT-5X3	DRL	5	4000	RoHS & Green	NIPDAU NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	(BEB, BES)	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74AHCT1G08 :

- Automotive : [SN74AHCT1G08-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

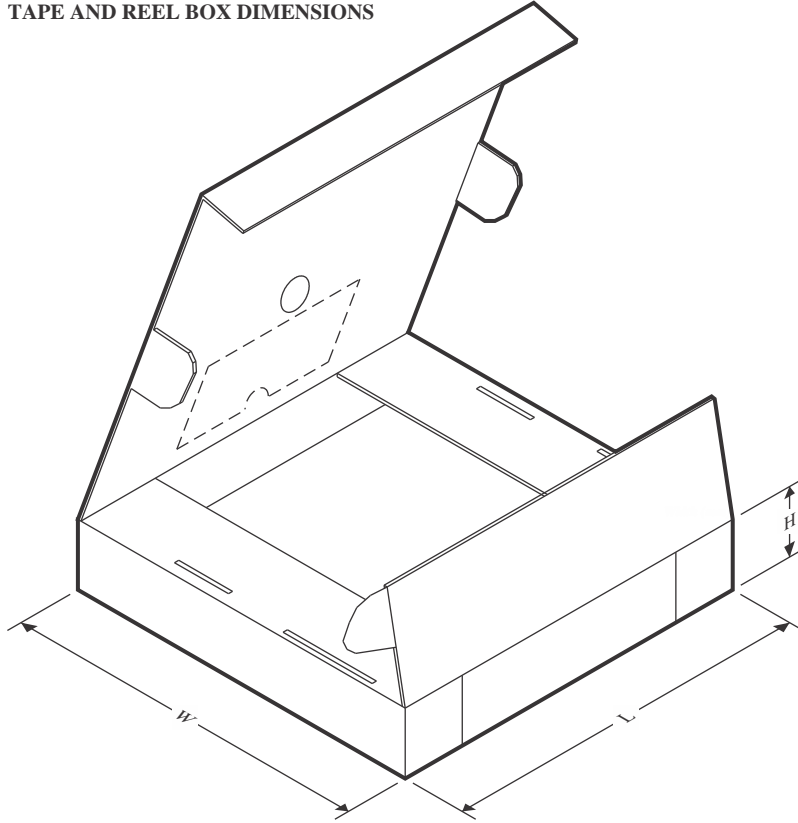
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AHCT1G08DBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHCT1G08DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
SN74AHCT1G08DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHCT1G08DCKR	SC70	DCK	5	3000	180.0	8.4	2.3	2.5	1.2	4.0	8.0	Q3
SN74AHCT1G08DCKR	SC70	DCK	5	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74AHCT1G08DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AHCT1G08DRLR	SOT-5X3	DRL	5	4000	180.0	8.4	1.98	1.78	0.69	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

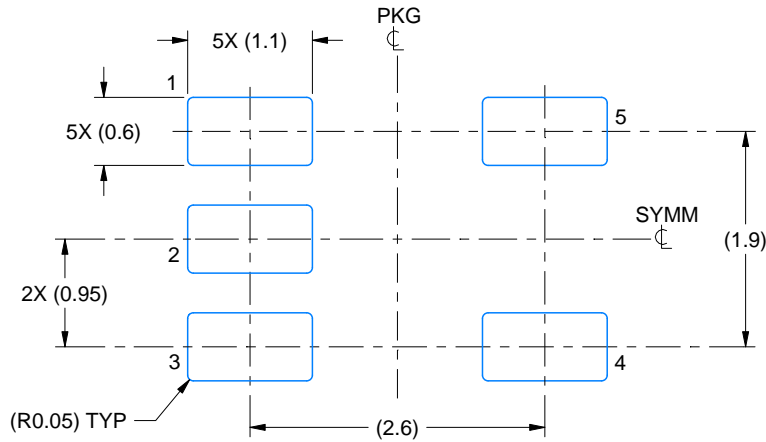
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AHCT1G08DBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74AHCT1G08DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74AHCT1G08DBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
SN74AHCT1G08DCKR	SC70	DCK	5	3000	210.0	185.0	35.0
SN74AHCT1G08DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
SN74AHCT1G08DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
SN74AHCT1G08DRLR	SOT-5X3	DRL	5	4000	202.0	201.0	28.0

EXAMPLE BOARD LAYOUT

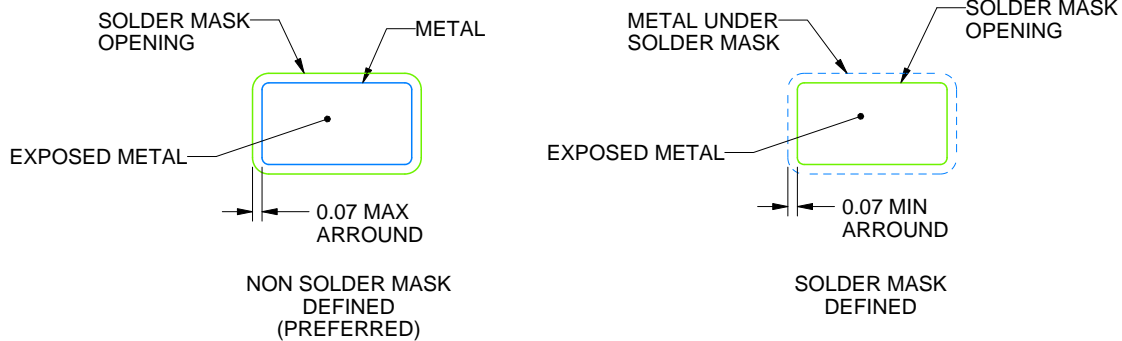
DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

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NOTES: (continued)

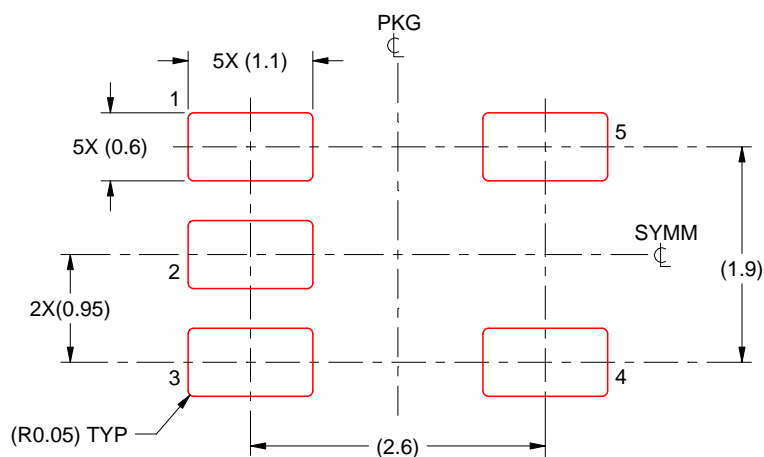
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/H 09/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

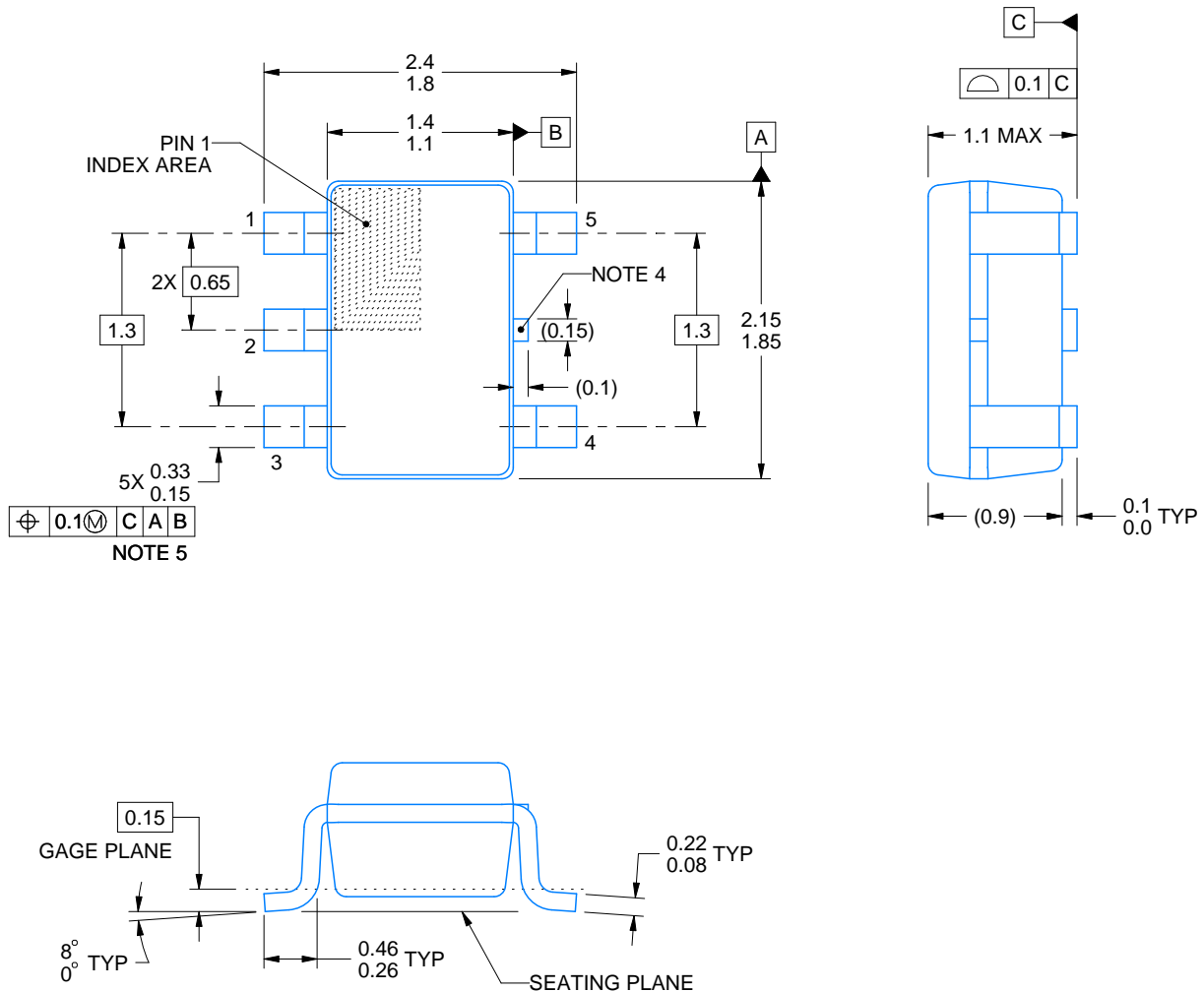
DCK0005A



PACKAGE OUTLINE

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



4214834/D 07/2023

NOTES:

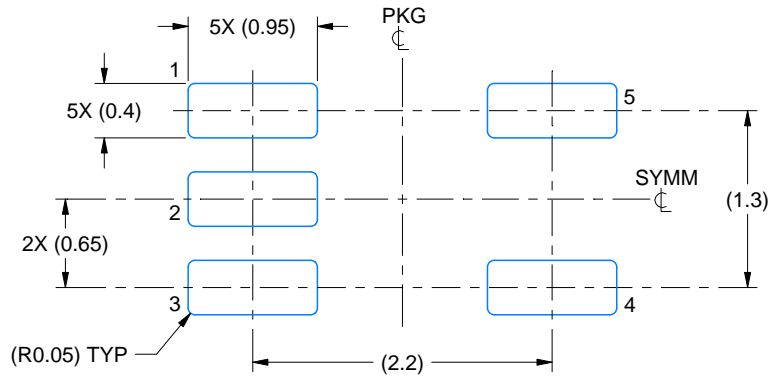
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-203.
4. Support pin may differ or may not be present.
5. Lead width does not comply with JEDEC.

EXAMPLE BOARD LAYOUT

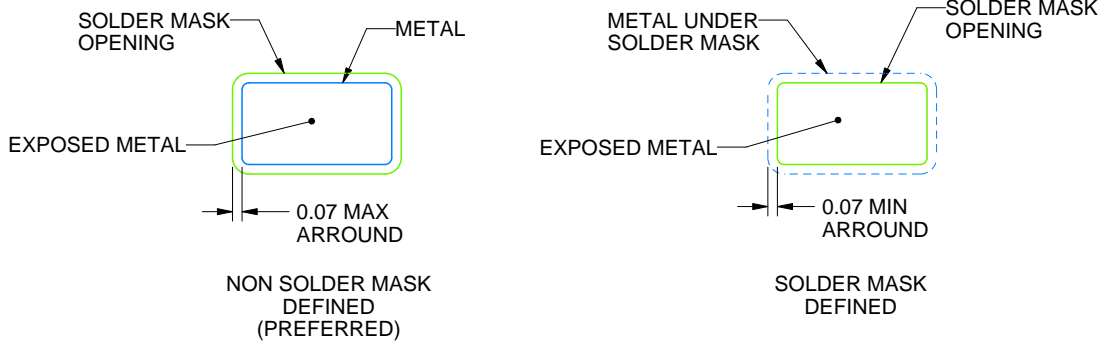
DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X

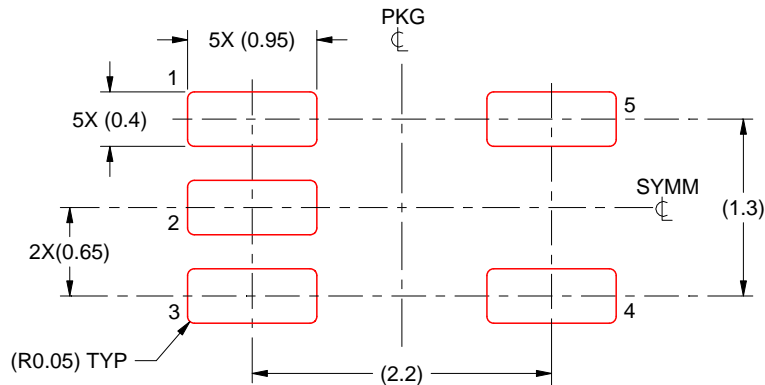


SOLDER MASK DETAILS

4214834/D 07/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



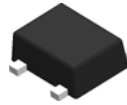
SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

4214834/D 07/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

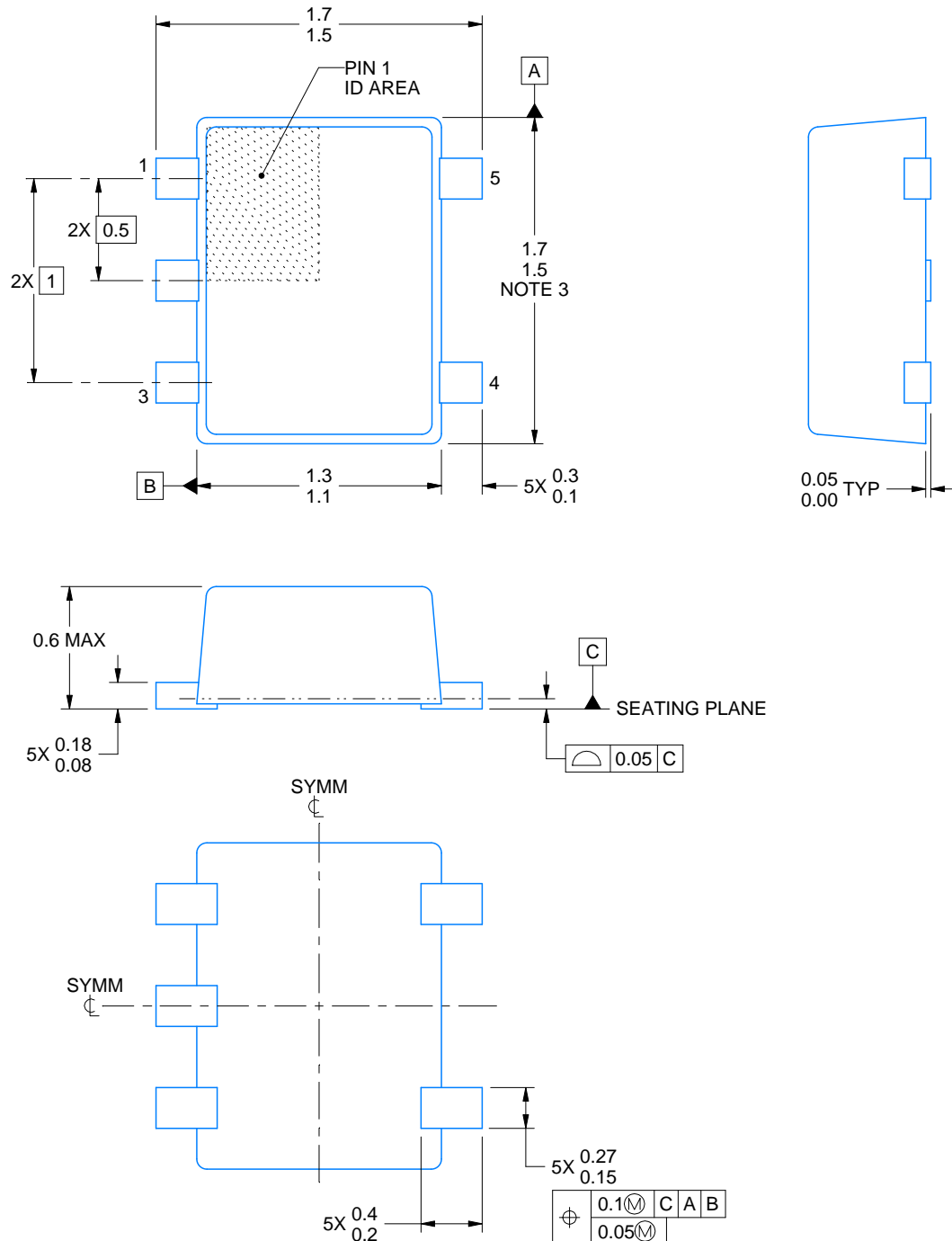
DRL0005A



PACKAGE OUTLINE

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



4220753/B 12/2020

NOTES:

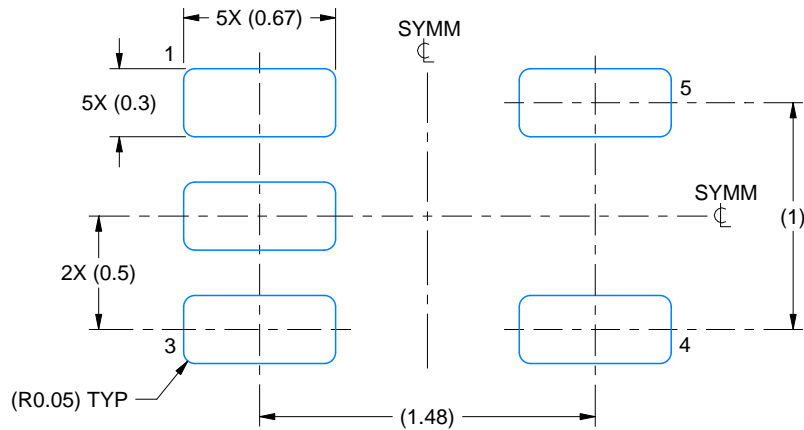
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD-1

EXAMPLE BOARD LAYOUT

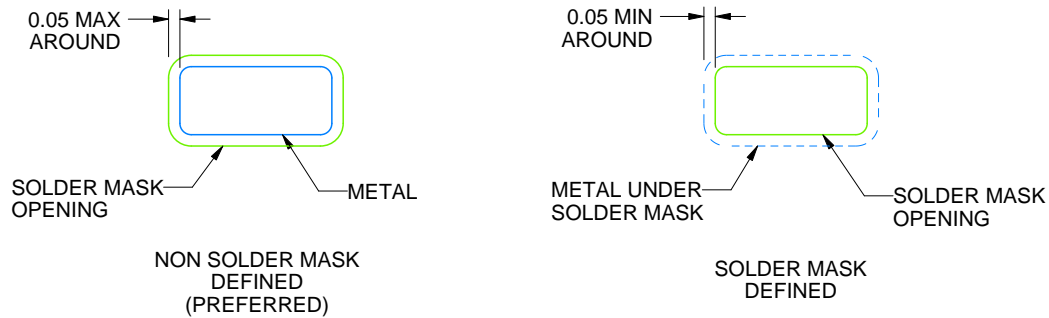
DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
SCALE:30X



SOLDERMASK DETAILS

4220753/B 12/2020

NOTES: (continued)

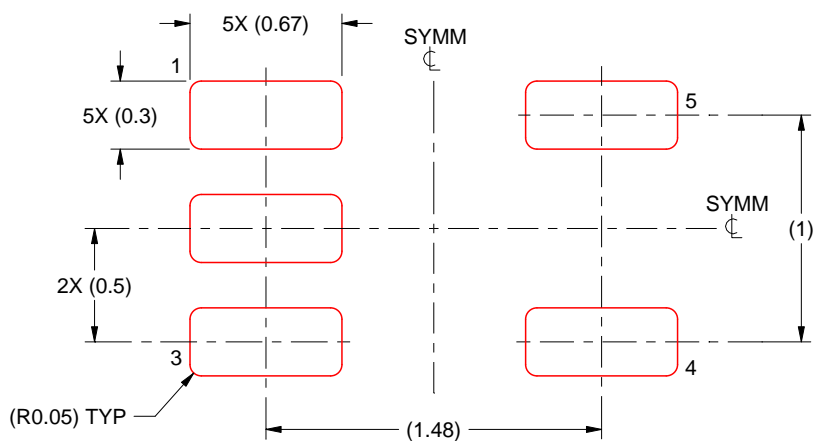
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:30X

4220753/B 12/2020

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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